

ASSIGNMENT RECORD
-PATENT

12-01-2003



102611426

11-19-03

To: Honorable Assistant Commissioner of Patents:

Please record the attached original document(s) or copy thereof.

- 1. Name of conveying party(ies)
 - a) Mark WESSELMANN
 - b) Kostadin PETKOV
 - c) Robert METTER
 - d) Michael S. WISNIESKI
 - e) John BOYD

- 2. Name and address of receiving party(ies):
 - a) Name: Advanced Material Sciences, Inc.
 - Address: 215 SW Washington Street, Suite 204
Portland, OR 97204

- 3. Nature of conveyance

<input checked="" type="checkbox"/> Assignment	<input type="checkbox"/> Merger
<input type="checkbox"/> Security Agreement	<input type="checkbox"/> Change of Name
<input type="checkbox"/> Other _____	<input type="checkbox"/> License Agreement

Execution Date: a), b), and e) 11/18/2003; c) 11/12/2003; and d) 11/11/2003

- 4. Application Number(s) or Patent Number(s): filed herewith **10716992**

The title of the (new) application is:

**PROTECTING THIN SEMICONDUCTOR WAFERS DURING BACK-GRINDING
IN HIGH-VOLUME PRODUCTION**

- 5. Please send all correspondence concerning this (these) documents to:

**CUSTOMER NUMBER 32,986
IPSG, P.C.
P. O. Box 700640
San Jose, CA 95170-0640
408-257-5500**

- 6. Total number of applications and patents involved: 1

- 7. Total fee (37 CFR 3.41): \$40.00

- Enclosed
- Any additional fees are authorized to be charged to Deposit Account No. 50-2284 (Order No. AMSI-P001)

- 8. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

- 9. Date: November 19, 2003

DAVID ASHBY

David C. Ashby
Registration No. 36,432

00000041 10716992
40.00 \$P

033187 U.S. PTO
10/7/16992
111903

ASSIGNMENT OF PATENT APPLICATION

(Accompanying Application)

WHEREAS I/we the undersigned inventor(s) have invented certain new and useful improvements as set for in the patent application entitled:

PROTECTING THIN SEMICONDUCTOR WAFERS DURING BACK-GRINDING IN HIGH-VOLUME PRODUCTION

(Atty. Docket No. AMSI-P001) for which I (we) have executed an application for a United States Letters Patent.

FOR GOOD AND VALUABLE CONSIDERATION, the receipt and sufficiency of which is hereby acknowledged, I/We the undersigned inventor(s) hereby:

- 1) Sell(s), assign(s) and transfer(s) to **Advanced Material Sciences, Inc.**, an Oregon corporation with a place of business located at 215 SW Washington Street, Suite 204, Portland, Oregon 97204 (hereinafter referred to as "ASSIGNEE"), the entire right title and interest in any and all improvements and inventions disclosed in, application(s) based upon, and Patent(s) (including foreign patents) granted upon the information which is disclosed in the above referenced application.
- 2) Authorize and request the Commissioner of Patents to issue any and all Letters Patents resulting from said application or any division(s), continuation(s), substitutes(s) or reissuc(s) thereof to the ASSIGNEE.
- 3) Agree to execute all papers and documents and, entirely at the ASSIGNEE's expense, perform any acts which are reasonably necessary in connection with the prosecution of said application, as well as any derivative and applications thereof, foreign applications based thereon, and/or the enforcement of patents resulting from such applications.
- 4) Agree that the terms, covenants and conditions of this assignment shall inure to the benefit of the Assignee, its successors, assigns and other legal representative, and shall be binding upon the inventor(s), as well as the inventor's heirs, legal representatives and assigns.
- 5) Warrant and represent that I/we have not entered, and will not enter into any assignment, contract, or understanding that conflicts with this assignment.

Signed on the date(s) indicated beside my (our) signature(s).

- 1) Date: 11/18/03 Signature: Mark A. Wesselmann
Typed Name: Mark WESSELMANN
- 2) Date: 11.18.03 Signature: K. Petkov
Typed Name: Kostadin PETKOV
- 3) Date: _____ Signature: _____
Typed Name: Robert METTER
- 4) Date: _____ Signature: _____
Typed Name: Michael S. WISNIESKI
- 6) Date: _____ Signature: _____
Typed Name: John BOYD

ASSIGNMENT OF PATENT APPLICATION

(Accompanying Application)

WHEREAS I/we the undersigned inventor(s) have invented certain new and useful improvements as set for in the patent application entitled:

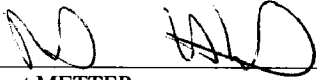
PROTECTING THIN SEMICONDUCTOR WAFERS DURING BACK-GRINDING IN HIGH-VOLUME PRODUCTION

(Atty. Docket No. AMSI-P001) for which I (we) have executed an application for a United States Letters Patent.

FOR GOOD AND VALUABLE CONSIDERATION, the receipt and sufficiency of which is hereby acknowledged, I/We the undersigned inventor(s) hereby:

- 1) Sell(s), assign(s) and transfer(s) to **Advanced Material Sciences, Inc.**, an Oregon corporation with a place of business located at 215 SW Washington Street, Suite 204, Portland, Oregon 97204 (hereinafter referred to as "ASSIGNEE"), the entire right title and interest in any and all improvements and inventions disclosed in, application(s) based upon, and Patent(s) (including foreign patents) granted upon the information which is disclosed in the above referenced application.
- 2) Authorize and request the Commissioner of Patents to issue any and all Letters Patents resulting from said application or any division(s), continuation(s), substitutes(s) or reissue(s) thereof to the ASSIGNEE.
- 3) Agree to execute all papers and documents and, entirely at the ASSIGNEE's expense, perform any acts which are reasonably necessary in connection with the prosecution of said application, as well as any derivative and applications thereof, foreign applications based thereon, and/or the enforcement of patents resulting from such applications.
- 4) Agree that the terms, covenants and conditions of this assignment shall inure to the benefit of the Assignee, its successors, assigns and other legal representative, and shall be binding upon the inventor(s), as well as the inventor's heirs, legal representatives and assigns.
- 5) Warrant and represent that I/we have not entered, and will not enter into any assignment, contract, or understanding that conflicts with this assignment.

Signed on the date(s) indicated beside my (our) signature(s).

- | | | |
|----|------------------------|--|
| 1) | Date: _____ | Signature: _____
Typed Name: Mark WESSELMANN |
| 2) | Date: _____ | Signature: _____
Typed Name: Kostadin PETKOV |
| 3) | Date: <u>12 Nov 03</u> | Signature: 
Typed Name: Robert METTER |
| 4) | Date: _____ | Signature: _____
Typed Name: Michael S. WISNIESKI |
| 6) | Date: _____ | Signature: _____
Typed Name: John BOYD |

ASSIGNMENT OF PATENT APPLICATION

(Accompanying Application)

WHEREAS I/we the undersigned inventor(s) have invented certain new and useful improvements as set for in the patent application entitled:

PROTECTING THIN SEMICONDUCTOR WAFERS DURING BACK-GRINDING IN HIGH-VOLUME PRODUCTION

(Atty. Docket No. AMSI-P001) for which I (we) have executed an application for a United States Letters Patent.

FOR GOOD AND VALUABLE CONSIDERATION, the receipt and sufficiency of which is hereby acknowledged, I/We the undersigned inventor(s) hereby:

- 1) Sell(s), assign(s) and transfer(s) to **Advanced Material Sciences, Inc.**, an Oregon corporation with a place of business located at 215 SW Washington Street, Suite 204, Portland, Oregon 97204 (hereinafter referred to as "ASSIGNEE"), the entire right title and interest in any and all improvements and inventions disclosed in, application(s) based upon, and Patent(s) (including foreign patents) granted upon the information which is disclosed in the above referenced application.
- 2) Authorize and request the Commissioner of Patents to issue any and all Letters Patents resulting from said application or any division(s), continuation(s), substitutes(s) or reissue(s) thereof to the ASSIGNEE.
- 3) Agree to execute all papers and documents and, entirely at the ASSIGNEE's expense, perform any acts which are reasonably necessary in connection with the prosecution of said application, as well as any derivative and applications thereof, foreign applications based thereon, and/or the enforcement of patents resulting from such applications.
- 4) Agree that the terms, covenants and conditions of this assignment shall inure to the benefit of the Assignee, its successors, assigns and other legal representative, and shall be binding upon the inventor(s), as well as the inventor's heirs, legal representatives and assigns.
- 5) Warrant and represent that I/we have not entered, and will not enter into any assignment, contract, or understanding that conflicts with this assignment.

Signed on the date(s) indicated beside my (our) signature(s).

- | | | |
|----|-------------------------|--|
| 1) | Date: _____ | Signature: _____
Typed Name: Mark WESSELMANN |
| 2) | Date: _____ | Signature: _____
Typed Name: Kostadin PETKOV |
| 3) | Date: _____ | Signature: _____
Typed Name: Robert METTER |
| 4) | Date: <u>11/11/2003</u> | Signature: <u><i>Michael S. Wisniewski</i></u>
Typed Name: Michael S. WISNIESKI |
| 6) | Date: _____ | Signature: _____
Typed Name: John BOYD |

ASSIGNMENT OF PATENT APPLICATION

(Accompanying Application)

WHEREAS I/we the undersigned inventor(s) have invented certain new and useful improvements as set for in the patent application entitled:


PROTECTING THIN SEMICONDUCTOR WAFERS DURING BACK-GRINDING IN HIGH-VOLUME PRODUCTION

(Atty. Docket No. AMSI-P001) for which I (we) have executed an application for a United States Letters Patent.

FOR GOOD AND VALUABLE CONSIDERATION, the receipt and sufficiency of which is hereby acknowledged, I/We the undersigned inventor(s) hereby:

- 1) Sell(s), assign(s) and transfer(s) to **Advanced Material Sciences, Inc.**, an Oregon corporation with a place of business located at 215 SW Washington Street, Suite 204, Portland, Oregon 97204 (hereinafter referred to as "ASSIGNEE"), the entire right title and interest in any and all improvements and inventions disclosed in, application(s) based upon, and Patent(s) (including foreign patents) granted upon the information which is disclosed in the above referenced application.
- 2) Authorize and request the Commissioner of Patents to issue any and all Letters Patents resulting from said application or any division(s), continuation(s), substitutes(s) or reissue(s) thereof to the ASSIGNEE.
- 3) Agree to execute all papers and documents and, entirely at the ASSIGNEE's expense, perform any acts which are reasonably necessary in connection with the prosecution of said application, as well as any derivative and applications thereof, foreign applications based thereon, and/or the enforcement of patents resulting from such applications.
- 4) Agree that the terms, covenants and conditions of this assignment shall inure to the benefit of the Assignee, its successors, assigns and other legal representative, and shall be binding upon the inventor(s), as well as the inventor's heirs, legal representatives and assigns.
- 5) Warrant and represent that I/we have not entered, and will not enter into any assignment, contract, or understanding that conflicts with this assignment.

Signed on the date(s) indicated beside my (our) signature(s).

- | | | |
|----|-----------------------|--|
| 1) | Date: _____ | Signature: _____
Typed Name: Mark WESSELMANN |
| 2) | Date: _____ | Signature: _____
Typed Name: Kostadin PETKOV |
| 3) | Date: _____ | Signature: _____
Typed Name: Robert METTER |
| 4) | Date: _____ | Signature: _____
Typed Name: Michael S. WISNIESKI |
| 6) | Date: <u>11/18/03</u> | Signature: 
Typed Name: John BOYD |